

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped Silicon	Silicon (Si)	7440-21-3	2.41947	100.0	8.48
Subtotal				2.41947	100	8.48
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.32526	100.0	1.14
Subtotal				0.32526	100	1.14
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.03064	2.0	0.1074
	Lead alloy	Silver (Ag)	7440-22-4	0.0383	2.5	0.13425
	Lead alloy	Lead (Pb)	7439-92-1	1.46319	95.5	5.12835
	Subtotal			1.53213	100	5.37
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01491	0.03	0.05226
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.01491	0.03	0.05226
	Copper alloy	Iron (Fe)	7439-89-6	0.0497	0.1	0.1742
	Copper alloy	Copper (Cu)	7440-50-8	49.62232	99.84	173.92128
Subtotal				49.70184	100	174.2
Post-plating	Pure metal	Tin (Sn)	7440-31-5	3.42378	100.0	12
Subtotal				3.42378	100	12
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.12988	5.0	7.465
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	6.38963	15.0	22.395
	Filler	Silica fused	60676-86-0	32.80008	77.0	114.961
	Flame retardant	Metal hydroxide		1.06494	2.5	3.7325
	Carbon Black	Carbon black	1333-86-4	0.21299	0.5	0.7465
Subtotal				42.59752	100	149.3
Total				100	100	350.49

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